



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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GROUP 1700

In re application of : Confirmation No. 3393
Isao NAKATANI : Docket No. 2001-0701A
Serial No. 09/857,258 : Group Art Unit 1765
Filed September 14, 2001 : Examiner Lan Vinh
DRY ETCHING :

#8/B
Jude
4/15/03

AMENDMENT

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

Responsive to the Office Action of December 4, 2002, the time for responding thereto being extended for one month in accordance with a Petition for Extension of Time submitted herewith, please amend the above-identified application as follows:

In the Specification:

Page 1, please replace the paragraph spanning lines 3-9 with the following rewritten paragraph:

BL The invention of the present application relates to a dry etching. More specifically, the invention of the present application relates to a dry etching method capable of fine processing an electrically conductive material, a heat transfer material, an electric contact material, etc., consisting of copper, silver, gold, or an alloy containing as a main component at least one of these metals.

Page 1, please replace the paragraph spanning line 15 through page 2, line 5, with the following rewritten paragraph:

BL The etching technique is a technique for fabricating a device which comprises transferring a resist pattern produced by lithography onto an object to be processed, i.e., to a semiconductor thin